

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3409026

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TSUTOMU HIYAMA	05/29/2015
RECEIVING PARTY DATA	
Name:	SENJU METAL INDUSTRY CO., LTD.
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14654956
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NAME OF SUBMITTER:	SUSAN D. PITCHFORD
SIGNATURE:	/SUSAN D. PITCHFORD/
DATE SIGNED:	06/23/2015
Total Attachments: 1	
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ASSIGNMENT - PATENT APPLICATION

WHEREAS, I, HIYAMA Tsutomu have invented certain new and useful improvements in
Gas-blowing-hole Array Structure and Soldering Apparatus

for which an application for United States Letters Patent is being filed as the U.S. National Stage of International Application PCT/JP2013/084296, filed December 20, 2013, and claiming priority to Japanese Patent application No. 2012-288293, filed December 28, 2012;and

WHEREAS, Senju Metal Industry Co., Ltd. of 23, Senju-Hashido-cho, Adachi-ku, Tokyo 120-8555, JAPAN (hereinafter "Assignee") desires to acquire an interest in said improvements and in the Letters Patent to be obtained therefor;

NOW THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are acknowledged, I/We hereby assign and transfer to Assignee, for the territory of the United States of America and all other countries, the entire right, title, and interest in and to said improvements and in and to said application and any Letters Patent that may be granted therefor in the United States and any other country including any division, continuation, substitute, renewal or reissue of said application or said Letters Patent.

I/We hereby agree to communicate to Assignee any facts known to me/us relating to said improvements, to testify as to the same in any interference or legal proceeding concerned therewith, to execute promptly and deliver to Assignee upon request any and all papers, instruments, declarations and affidavits required to apply for, obtain, maintain and enforce said Letters Patent, and generally to do everything necessary or desirable to vest and perfect title thereto in Assignee.

This assignment is binding upon me/us and my/our heirs, successors, and legal representatives, and shall inure to the benefit of Assignee, its successors, assigns and nominees.

I/We agree that no attorney/client or other fiduciary relationship exists between me/us and CHERNOFF, VILHAUER, MCCLUNG & STENZEL, LLP.
INVENTOR(S):

TSUTOMU HIYAMA
HIYAMA Tsutomu

May 29, 2015
Date